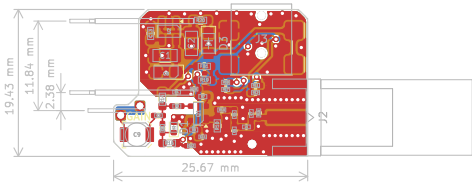


Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	JLCPCB Soldermask	0.01524 mm	Not specified	3.8	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	Nan Ya Plastics NP-155F 3313	0.0994 mm	FR4 natural	4.1	0.02
In1.Cu	copper		0.0152 mm		1	0
Dielectric	core	Nan Ya Plastics NP-155F Core	1.265 mm	FR4 natural	4.43	0.02
In2.Cu	copper		0.0152 mm		1	0
Dielectric	prepreg	Nan Ya Plastics NP-155F 3313	0.0994 mm	FR4 natural	4.1	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	JLCPCB Soldermask	0.01524 mm	Not specified	3.8	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5947 mm
Board overall dimensions:	25.6700 mm x 19.4350 mm		
Min track/spacing:	0.1000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Petr Polášek

Sheet:

File: LowCapacitanceProbe.kicad_pcb

Title: Low Capacitance (<1 pF) 10:1 AC 1+ GHz Probe

Size: A5

Date: 2025-04-11

Rev: 1.0.0

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